

Yue Zhang

List of Publications by Year in descending order

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12
papers

210
citations

1478505

6
h-index

1872680

6
g-index

13
all docs

13
docs citations

13
times ranked

169
citing authors

#	ARTICLE	IF	CITATIONS
1	Thermal Design and Constraints for Heterogeneous Integrated Chip Stacks and Isolation Technology Using Air Gap and Thermal Bridge. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 1914-1924.	2.5	45
2	Silicon Micropin-Fin Heat Sink With Integrated TSVs for 3-D ICs: Tradeoff Analysis and Experimental Testing. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 1842-1850.	2.5	38
3	3-D Stacked Tier-Specific Microfluidic Cooling for Heterogeneous 3-D ICs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 1811-1819.	2.5	24
4	Independent interlayer microfluidic cooling for heterogeneous 3D IC applications. Electronics Letters, 2013, 49, 404-406.	1.0	24
5	Within-tier cooling and thermal isolation technologies for heterogeneous 3D ICs. , 2013, , .		18
6	Thermal and electrical effects of staggered micropin-fin dimensions for cooling of 3D microsystems. , 2014, , .		18
7	Thermal Isolation Using Air Gap and Mechanically Flexible Interconnects for Heterogeneous 3-D ICs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 31-39.	2.5	13
8	Fine pitch TSV integration in silicon micropin-fin heat sinks for 3D ICs. , 2012, , .		9
9	High aspect ratio TSVs in micropin-fin heat sinks for 3D ICs. , 2012, , .		8
10	Fabrication and Characterization of Electrical Interconnects and Microfluidic Cooling for 3D ICS With Silicon Interposer. Heat Transfer Engineering, 2016, 37, 903-911.	1.9	6
11	Tier-independent microfluidic cooling for heterogeneous 3D ICs with nonuniform power dissipation. , 2013, , .		3
12	Design, fabrication and assembly of a novel electrical and microfluidic I/Os for 3-D chip stack and silicon interposer. , 2013, , .		3